## **MA2YD15**

### Silicon epitaxial planar type

For high frequency rectification

#### ■ Features

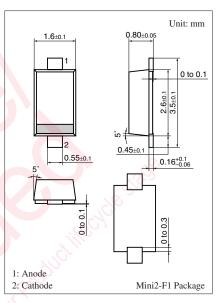
- Forward current (Average)  $I_{F(AV)} = 1$  A rectification is possible
- ullet Low forward voltage  $V_F$
- Small reverse current I<sub>R</sub>

#### ■ Absolute Maximum Ratings $T_a = 25$ °C

Parameter	Symbol	Rating	Unit
Reverse voltage	$V_R$	20	V
Repetitive peak reverse voltage	$V_{RRM}$	25	V
Forward current (Average) *1	I <sub>F(AV)</sub>	1.0	A
Non-repetitive peak forward surge current *2	$I_{FSM}$	3	A
Junction temperature	$T_{j}$	125	°C
Storage temperature	$T_{stg}$	-55 to +125	°C



\*2: The peak-to-peak value in one cycle of 50 Hz sine wave (non-repetitive)



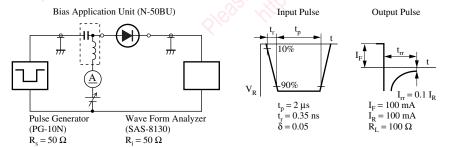
Marking Symbol: 2R

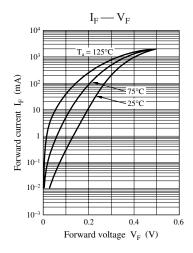
### ■ Electrical Characteristics $T_a = 25$ °C $\pm 3$ °C

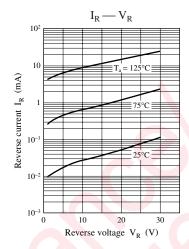
Parameter	Symbol	Conditions	Min	Тур	Max	Unit
Forward voltage	V <sub>F</sub>	$I_F = 1.0 \text{ A}$	~0,7/		0.45	V
Reverse current	$I_R$	$V_R = 20 \text{ V}$	20	55	100	μΑ
Terminal capacitance	$C_{t}$	$V_R = 0 V, f = 1 MHz$	10g)	120		pF
Reverse recovery time *	t <sub>rr</sub>	$I_F = I_R = 100 \text{ mA}$	7.7	10		ns
-0,1		$I_{rr} = 0.1 I_R, R_L = 100 \Omega$	) `			

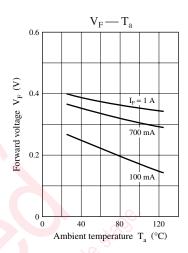
Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7031 measuring methods for diodes.

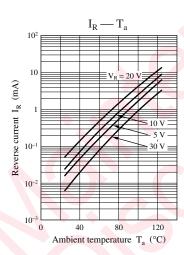
- This product is sensitive to electric shock (static electricity, etc.). Due attention must be paid on the charge of a human body and the leakage of current from the operating equipment.
- 3. \*: t<sub>rr</sub> measurement circuit











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